© Cor	erial Composition pyright 2005. IPC, B ational and Pan-Ame	annockburn, Ill	linois. All rights reserv	ed under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances w all lower	vithin the manufactu level materials for w	rer listed ite which the ma	m. Note: i nufacturer	f the item is an as has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi 					ials and Mf	als and Mfg Information			
upplier Information														
Company name* Con			Company unique ID			Unique ID Authority				Response	Response Date*			
onsemi										2023-06-08				
Contact Name T			Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards F			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title			Title - Representative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item N	Requester Item Number Mfr Iter		m Number Mfr Item Name			Effective Date	ective Date Version Manufacturing Site		anufacturing Site	W	eight*	UOM	Unit Type	
	I	.P2951ACD-3.	.3R2G ANA 100MA	ANA 100MA 3.3V LDO VREG		2023-06-08		CNW		7	1.99	mg	Each	
Ianufacturing Procce	ess Information													
Terminal Plating / Grid Array Material Terr		Termina	rminal Base Alloy J-STD-020 MSL		SL Rating	Peak Process Body Temperature		Max Time at Peak	. Temperatu	re Numb	er of Reflow Cyc	les		
Matte Tin (Sn) - annealed C		CU Allo	Alloy 1			260	50 C 30		30	seconds 3				
omments														
vel 1 - maximum time at po	eak temperature du	ring soldering	g is 10-30 seconds											
or more information regar	ding material comp	osition please	refer to page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg		Epoxy resin	proprietary data		0.24	mg
			Supplier	Ethylene dimethacrylate	97-90-5		0.12	mg
			Supplier	Silver (Ag)	7440-22-4		1.92	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.12	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.2257	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0451	mg
			Supplier	Iron (Fe)	7439-89-6		0.8838	mg
			Supplier	Copper (Cu)	7440-50-8		36.4441	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0113	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
lating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Cu	0.18	mg	Supplier	Copper (Cu)	7440-50-8		0.18	mg